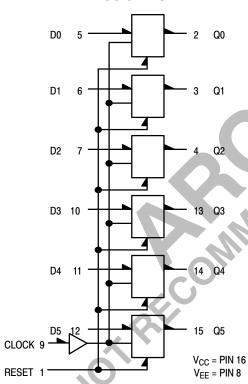
Hex D Master-Slave Flip-Flop with Reset

The MC10186 contains six high–speed, master slave type "D" flip–flops. Clocking is common to all six flip–flops. Data is entered into the master when the clock is low. Master to slave data transfer takes place on the positive–going Clock transition. Thus, outputs may change only on a positive–going Clock transition. A change in the information present at the data (D) input will not affect the output information any other time due to the master–slave construction of this device. A COMMON RESET IS INCLUDED IN THIS CIRCUIT. RESET ONLY FUNCTIONS WHEN CLOCK IS LOW.

- $P_D = 460 \text{ mW typ/pkg (No Load)}$
- $f_{toggle} = 150 \text{ MHz (typ)}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)

LOGIC DIAGRAM



CLOCKED TRUTH TABLE

R	С	D	Qn + 1
L	L	Х	Q _n
L	H*	L	L
L	H*	Н	Н
Н	L	Χ	L

^{*}A clock H is a clock transition from a low to a high state.



ON Semiconductor

http://onsemi.com



CDIP-16 L SUFFIX CASE 620



MARKING

DIAGRAMS



PDIP-16 P SUFFIX CASE 648





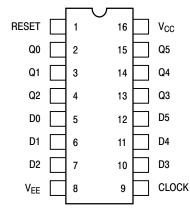
PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

_		_		
Device	Package	Shipping		
MC10186L	CDIP-16	25 Units / Rail		
MC10186P	PDIP-16	25 Units / Rail		
MC10186FN	PLCC-20	46 Units / Rail		

ELECTRICAL CHARACTERISTICS

		Pin	Test Limits -30°C +25°C +85°C					1		
Observations	_	Under	−30°C		N/I:-	+25°C				┧
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Uni
Power Supply Drain Current	I _E	8		121		88	110		121	mAd
Input Current	I _{inH}	5 9		350 495			220 310		220 310	μAd
		1		920			575		575	
	I _{inL}	5	0.5		0.5			0.3		μAc
Output Voltage Logic 1	V _{OH}	2†	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdd
0 :	.,	15†	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Output Voltage Logic 0	V _{OL}	2† 15†	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdo
Threshold Voltage Logic 1	V _{OHA}	2†	-1.080		-0.980			-0.910		Vd
		15†	-1.080		-0.980			-0.910		厂
Threshold Voltage Logic 0	V_{OLA}	2†		-1.655			-1.630		-1.595	Vd
Outlable Trace (500 Leed)		15†		-1.655			-1.630		-1.595	
Switching Times (50 Ω Load)			4.0	4.0	4.0	2.5	4.5	10		ns
Propagation Delay	t ₁₊₃ _ t ₁₊₄ _	3 4	1.6 1.6	4.6 4.6	1.6 1.6	2.5 2.5	4.5 4.5	1.6 1.6	5.0 5.0	
	t ₉₊₂₊	2	1.6	4.6	1.6	3.5	4.5	1.6	5.0	
	t ₉₊₂₋	2	1.6	4.6	1.6	3.5	4.5	1.6	5.0	
Rise Time (20 to 80%)	t ₂₊	2	1.0	4.1	1.1	1.8	4.0	1.1	4.4	
Fall Time (20 to 80%)	t ₂₋	2	1.0	4.1	1.1	1.8	4.0	1.1	4.4	
Setup Time	t _{setup}	2	2.5		2.5	2.5		2.5		ns
Hold Time	t _{hold}	2	1.5		1.5	-1.5		1.5		ns
Toggle Frequency (Max)	f _{tog}	2	125		125	150		125		МН
Output level to be measured a		V _{IL}				input (Pin	,			

V_{IH} appears at clock input (Pin 9).

ELECTRICAL CHARACTERISTICS (continued)

					TEST VOL	TAGE VALU	IES (Volts)		
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
		+85°C	-0.700	-1.825	-1.035	-1.440	− 5.2		
Pin			TEST V	OLTAGE AP	PLIED TO PI	NS LISTED I	BELOW		
Characteris	stic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	urrent	ΙE	8					8	16
Input Current		l _{inH}	5 9 1	5 9 1				8 8 8	16 16 16
		I _{inL}	5		5			8	16
Output Voltage	Logic 1	V _{OH}	2† 15†	5 12				8 8	16 16
Output Voltage	Logic 0	V _{OL}	2† 15†		5 12			8 8	16 16
Threshold Voltage	Logic 1	V _{OHA}	2† 15†			5 12	12	8 8	16 16
Threshold Voltage	Logic 0	V _{OLA}	2† 15†				5 12	8 8	16 16
Switching Times	(50Ω Load)			+1.11Vdc	+0.31V	Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay		t ₁₊₃ _ t ₁₊₄ _ t ₉₊₂₊ t ₉₊₂ _	3 4 2 2	6 7		1, 9 1, 9 5, 9 5, 9	3 4 2 2	8 8 8	16 16 16 16
Rise Time	(20 to 80%)	t ₂₊	2		.0	5, 9	2	8	16
Fall Time	(20 to 80%)	t ₂₋	2			5, 9	2	8	16
Setup Time		t _{setup}	2			5, 9	2	8	16
Hold Time		t _{hold}	2	167		5, 9	2	8	16
Toggle Frequency (Ma	x)	f _{tog}	2					8	16

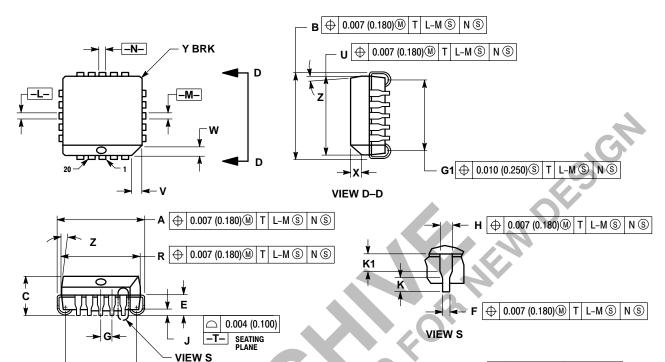
[†] Output level to be measured after clock pulse. VIH appears at clock input (Pin 9).

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

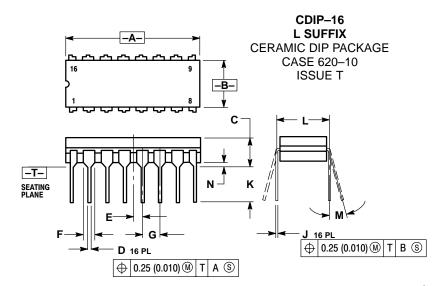
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS



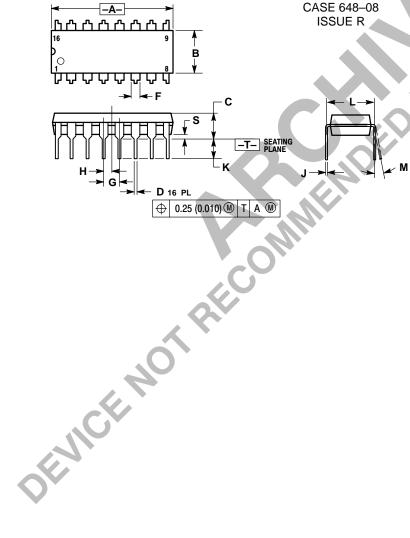
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL
 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIN	IETERS		
DIM	MIN MAX		MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
С		0.200		5.08		
D	0.015	0.020	0.39	0.50		
E	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300	BSC	7.62 BSC			
М	0 °	15°	0 °	15°		
N	0.020	0.040	0.51	1.01		

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54 BSC	
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

Notes



Notes





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